

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sandhu, et al.

Serial No.: 09/627,381

Filed: July 28, 2000

For: INTERLEVEL DIELECTRIC STRUCTURE
AND METHOD OF FORMING SAME

Examiner: Not yet assigned



INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that any of these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record believes that the enclosed art is the closest to the claimed invention (taken in its

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entirety) of which the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

Statement of References Previously Disclosed
Under 37 C.F.R. § 1.98(d)

The following listed references are not enclosed because, under 37 C.F.R. § 1.98(d), they were previously cited by or submitted to the Office in application number 08/677,514, filed on July 10, 1996, which is relied upon for an earlier filing date under 35 U.S.C. § 120.

United States Patent Documents

<u>Patent Number</u>	<u>Issue Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub Class</u>	<u>Filing Date</u>
5,445,996	8/95	Kodera et al.	438	633	
5,486,493	1/96	Jeng	438	623	
5,399,235	3/95	Mutsaers et al.	438	633	
5,420,075	5/95	Homma et al.	438	624	
5,599,740	2/97	Jang et al.	438	626	
5,677,239	10/97	Isobe	438	633	
5,795,829	8/98	Shen	438	694	
5,708,303	1/98	Jeng	257	758	

Other Documents

M.K. Jain et al., "Advanced Metalization and Interconnect systems for ULSI Applications: Homogenous and Multilayer Low-K Interlevel Dielectric Architectures for Capacitance Reduction," Conference at University of California, Berkeley, California, October 1996.

Tetsuya Homma, "Fluorinated SiO₂ Films for Interlayer Dielectrics in Quarter-Micron ULSI Multilevel Interconnections," Mat. Res. Soc. Symp. Proc., vol. 381, pp. 239-248, 1995.

J. Wary et al., "Vacuum-Deposited Parylene AF-4: A Thermally Stable, Low Dielectric Constant Polymer For Interlayer Dielectric Use," DUMIC Conference, pp. 207-213, February, 1996.

Dated this 15 day of October, 2000.

Respectfully submitted,



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